

**The Joint International EUROSOI Workshop and International Conference on Ultimate Integration on Silicon (EUROSOI-ULIS)** is a three days meeting bringing together the experts from Industry and Academia in technology, physics, modeling, simulation, and characterization of advanced nano-scale semiconductor-on-insulator and silicon-compatible devices from Europe and all over the world. For more than ten years the EUROSOI Workshop and the ULIS Conference provided a platform for the European micro- and nanoelectronic community to share the most recent advances, discuss the hottest topics in the field and outline current trends defining the future progress. As the future of microelectronics is believed to be determined by fully depleted SOI and FinFET devices enabling new functionalities, the two sister conferences were merged in 2015 in order to further boost their importance and scientific impact. Encouraged by the great success of the first joint EUROSOI-ULIS event, the second joint EUROSOI-ULIS 2016 Conference is hosted by the Institute for Microelectronics, TU Wien, Austria. The aim of the EUROSOI-ULIS Conference is to provide an open forum for the presentation and discussion of recent advances in the fields of More Moore, More than Moore, and Beyond CMOS applications. The hot topics introduced by outstanding international invited speakers will further be discussed at the sessions with a particular focus on modern SOI technology and advanced nanoscale devices. The Conference Committees and organizers hope you will enjoy the conference and the social program.

#### Conference Chairs

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